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LRDIMM System-Level Validation Results on Intel® Xeon® E5-2600 v2 Processor Family

Listed below are the results from a small sample of DDR3 LRDIMMs tested on Intel® Xeon® E5-2600 v2 processor family. We are providing this information as a guide to module compatibility with Intel server reference platforms. This testing is not intended to replace the normal OEM qualification process. For results on specific Intel® motherboards or OEM production motherboards, please refer to the OEM's list of qualified memory suppliers.

The configurations validated only for the same supplier and same part number across memory channels

Updated / New Part

LRDIMM DDR3-1866 Quad Rank 1.5V 1 DIMM Per Channel / 3Slot Per Channel / 4Channel

DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
Crucial	CT32G3ELSDQ4186D.36DED	32GB	13	C	Micron	MT41K2G4TRF-107:E	4Gb	x4	1334	Inphi	GS02B	1
Elpida	EBJ34LH4B6PA-JS-F	32GB	13	K	Elpida	EDJ8404B6HB-JS-F	4Gb	x4	1311	Inphi	GS02B	1
Elpida	EBJ34LH4B6PA-JS-F	32GB	13	K	Elpida	EDJ8404B6HB-JS-F	4Gb	x4	1311	Montage	C1	1
Micron	MT72JSZS4G72LZ-1G9E2A7	32GB	13	C	Micron	MT41K2G4TRF-107:E	4Gb	x4	1334	Inphi	GS02B	1
Micron	MT72JSZS4G72LZ-1G9E2C3	32GB	13	C	Micron	MT41K2G4TRF-107:E	4Gb	x4	1334	Montage	C1	1
Samsung	M386B4G70DM0-CMA	32GB	13	C	Samsung	K4B8G0446D-MCMA	4Gb	x4	1328	Inphi	GS02B	1
SK hynix	HMT84GL7AMR4C-RD	32GB	13	C	SK hynix	H5TQ8G43AMR-RDC	4Gb	x4	1318	Montage	C1	1
SK hynix	HMT84GL7AMR4C-RD	32GB	13	C	SK hynix	H5TQ8G43AMR-RDC	4Gb	x4	1318	Inphi	GS02B	1
SK hynix	HMT84GL7BMR4C-RD	32GB	13	C	SK hynix	H5TQ8G43BMR-RDC	4Gb	x4	1442	Montage	C1	1
SK hynix	HMT84GL7BMR4C-RD	32GB	13	C	SK hynix	H5TQ8G43BMR-RDC	4Gb	x4	1442	Inphi	GS02B	1

1 - DDP (Dual-Die Package)

LRDIMM DDR3-1600 Quad Rank 1.5V 2 DIMM Per Channel / 3Slot Per Channel / 4Channel

DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
Crucial	CT32G3ELSLQ4160B.36DED	32GB	11	C	Micron	MT41K2G4TRF-125:E	4Gb	x4	1334	Inphi	GS02B	1
Elpida	EBJ34LH4E6PA-GN-F	32GB	11	K	Elpida	EDJ8404E6HB-GN-F	4Gb	x4	1311	Montage	C1	1
Micron	MT72KSZS4G72LZ-1G6E2A7	32GB	11	C	Micron	MT41K2G4TRF-125:E	4Gb	x4	1334	Inphi	GS02B	1
Micron	MT72KSZS4G72LZ-1G6E2C3	32GB	11	C	Micron	MT41K2G4TRF-125:E	4Gb	x4	1250	Montage	C1	1
Samsung	M386B4G70DM0-YK0	32GB	11	C	Samsung	K4B8G0446D-MYK0	4Gb	x4	1328	Montage	C1	1
SK hynix	HMT84GL7AMR4A-PB	32GB	11	C	SK hynix	H5TC8G43AMR-PBA	4Gb	x4	1318	Montage	C1	1
SK hynix	HMT84GL7AMR4A-PB	32GB	11	C	SK hynix	H5TC8G43AMR-PBA	4Gb	x4	1318	Inphi	GS02B	1
SK hynix	HMT84GL7BMR4A-PB	32GB	11	C	SK hynix	H5TC8G43BMR-PBA	4Gb	x4	1442	Montage	C1	1

1 - DDP (Dual-Die Package)

LRDIMM 8R DDR3-1066 1.5V 3DIMM Per Channel / 3Slot Per Channel/ 4Channel													
DIMM					**DRAM**					**Buffer**		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
Elpida	EBJ67LJ4B3HA-GN-F	64GB	9	E	Elpida	EDJA504B3HB-GN-F	4Gb	x4	1313	Montage	C1	1
Micron	MT144KSZQ8G72LZ-1G4E1A7	64GB	9	E	Micron	MT41K4G4SMA-15E:E	4Gb	x4	1334	Inphi	GS02B	1
Micron	MT144KSZQ8G72LZ-1G4E1C3	64GB	9	E	Micron	MT41K4G4SMA-15E:E	4Gb	x4	1334	Montage	C1	1
Samsung	M386B8G70DE0-YH9	64GB	9	E	Samsung	K4BAG0446D-EYH9	4Gb	x4	1341	Inphi	GS02B	1
SK hynix	HMTA8GL7AHR4C-PB	64GB	11	E	SK hynix	H5TQAG43AHR-PBC	4Gb	x4	1330	Inphi	GS02B	1
SK hynix	HMTA8GL7AHR4C-PB	64GB	11	E	SK hynix	H5TQAG43AHR-PBC	4Gb	x4	1330	Montage	C1	1

1 - QDP (Quad-Die Package)

Updated on Jan 16, 2015

Approved Test Labs:

The following test labs have the capability of performing the DDR3 LRDIMM system-level testing. For further information please contact:

Platform Memory Operations Lab
Advanced Validation Labs
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